

MIL-T-10727

REVISION C
6/30/1989

TIN PLATING: ELECTRODEPOSITED
OR HOT-DIPPED, FOR FERROUS AND
NONFERROUS METALS



THIS SPECIFICATION COVERS THE REQUIREMENTS FOR ELECTRODEPOSITED TIN AND HOT-DIPPED TIN COATINGS ON FERROUS AND NONFERROUS METALS.

<u>MIL-T-10727 DEPARTURES</u>	<u>EFF DATE</u>	<u>SUBCONTRACTOR(S) AFFECTED</u>	<u>ON MODELS</u>	<u>MFG DEPTS OF DIV BELOW AFFECTED</u>	<u>REASON</u>
NOTICE 1	2/7/1997	ALL			MIL-T- 10727C, DATED 30 JUNE 1989, IS HEREBY CANCELED. FUTURE REQUIREMENTS FOR TIN PLATING ELECTRODEPOSITED (TYPE 1) SHOULD REFER TO ASTM B 545, "STANDARD SPECIFICATION FOR ELECTRODEPOSITED COATINGS OF TIN", (DOD ADOPTED). FUTURE REQUIREMENTS FOR TIN FOR USE IN HOT-DIPPED APPLICATIONS (TYPE H) SHOULD REFER TO ASTM B 339, "TIN, PIG", GRADE A, (DOD ADOPTED).